

SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: FTG Circuits Fredericksburg Inc. 1026 Warrenton Road, Fredericksburg, VA, 22406-6200 US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 6T499 Phone: 540-753-5511, x177 Fax: 540-752-2109 E-Mail: quality@colonialcircuits.com
------------------------------------------------------------------------------------------------------------------------------------------	--------------------------------------------------------	----------------------------------------------------------------------------------------------------------------------------------------

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQE-04-6002
 Rigid Base Material: GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 14
 Max. Board Thickness: .088"
 Min. Hole Size: .021" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 4.2:1 Through-Hole
 Min. Conductor Width/Space: .006"/.005"
 Hole Preparation: Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Carbon-based
 Copper Plating: Direct Current Plate
 Solder Resist: Liquid Photoimageable
 Finish System: ENIG, HASL

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQE-04-6002, VQE-20-034719
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 16
 Max. Board Thickness: .127"
 Min. Hole Size: .015"
 Aspect Ratio: 8.5:1 Through-Hole
 Min. Conductor Width/Space: .005"/.004"
 Hole Preparation: Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Carbon-based
 Copper Plating: Direct Current Plate
 Solder Resist: Liquid Photoimageable
 Finish System: ENIG, HASL

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION

Specification: MIL-PRF-31032/3, MIL-PRF-31032/4
 Qualification Letters: VQE-04-6002
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant; GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
 Flex Base Material: Copper Clad Polyimide with Acrylic Adhesive
 Max. Panel Size: 12" x 18"
 Max. Number of Layers: 10
 Max. Board Thickness: .093"
 Min. Hole Size: .025" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 3.7:1 Through-Hole
 Min. Conductor Width/Space: .005"/.005"
 Hole Preparation: Plasma Desmear, Plasma Etchback
 Hole Wall Conductive Coating: Carbon-based
 Copper Plating: Direct Current Plate
 Solder Resist: Liquid Photoimageable
 Finish System: ENIG, HASL
 Flex Usage: Use A (Flex During Installation),